# LOW PROFILE SINGLE CONACT 201-01-154



1.50±0.25mm

1

70-9155-001-615-00X with nominal working height

1.25mm to 1.75mm. Mated to a pad on a PCB or a

1.50mm can be used with vertical spacing of

device, for example a battery.

### 1. SPECIFICATION DISTRIBUTION

No restrictions for issue

#### SCOPE 2.

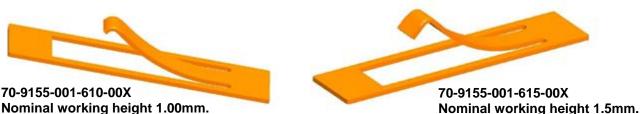
This specification contains the application notes for the 9155 low profile contact.

#### 3. RELATED DOCUMENTS

70-9155-001-6XX-00X - Sales Drawing 201-01-153 - Product Specification

Note: The colours used in this specification are for clarity only.

#### 9155 LOW PROFILE CONTACTS 4.

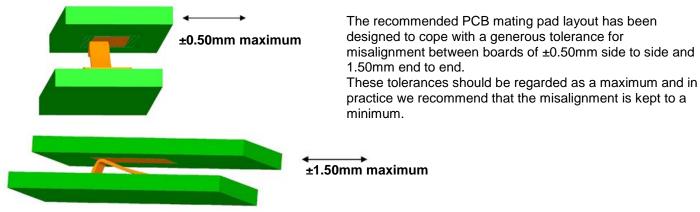


#### WORKING HEIGHT 4.1.



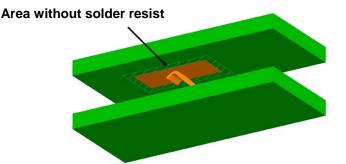
70-9155-001-610-00X with nominal working height 1.00mm can be used with vertical spacing of 0.75mm to 1.25mm. Mated to a pad on a PCB or a device for example a battery.

#### MAXIMUM PCB MISALIGNMENT 4.2.



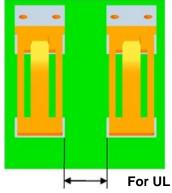


## 4.3. MATING PAD ON PCB



A single pad plated with gold over a nickel under-plate is recommended for good contact under all conditions. Dimensions of pad refer to sales drawing. An area around the mating pad approximately 0.5mm wide should be free of solder resist. This prevents the contact nose riding up on the resist and loosing contact with the pad, see also section 4.2 on misalignment above.

## 4.4. UL REQUIREMENTS FOR PAD SPACING



UL approval based on 3.2mm gap between pads, contact centre spacing 5.9mm.

For non UL applications the gap may be reduced at the customers discretion depending on voltage applied.

## For UL application 3.2mm minimum

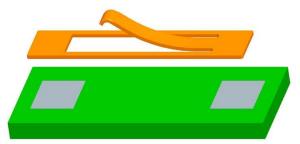
5. CONTACT SMT ASSEMBLY

## 5.1. PICK AND PLACE



The recommended pick and place area (highlighted here in blue) is 2.70mm wide by 1.75mm long.

## 5.2. SMT SOLDER PADS

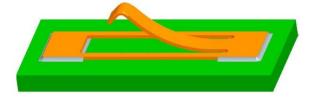


2 solder pads, refer to sales drawing for dimensions. Placing a pad between these is not recommended as it may affect contact performance.

The space between the pads should be kept clear of all tacks and components.

It is recommended that solder pads are tin plated.

## 5.3. SMT SOLDERING



After SMT the contact should be sitting square on the pads and have small fillets all around soldered edges.

2